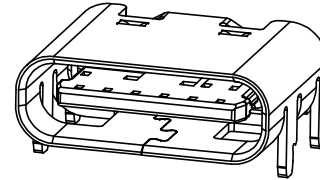
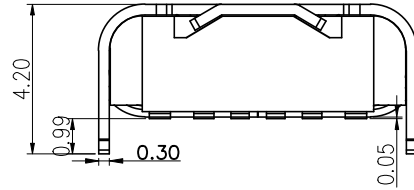
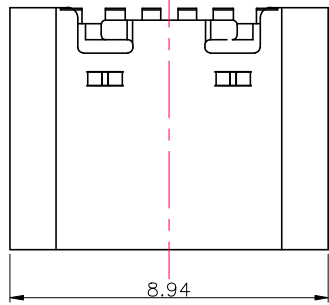


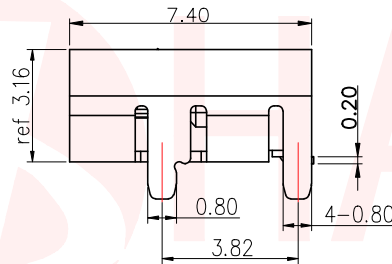
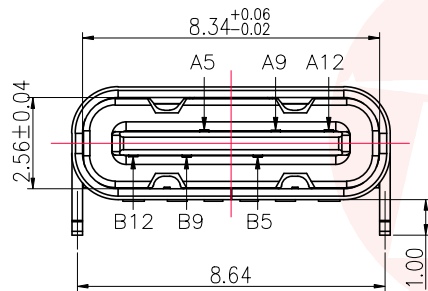


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



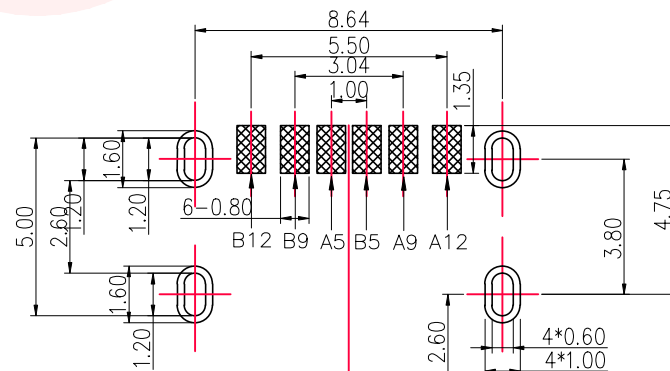
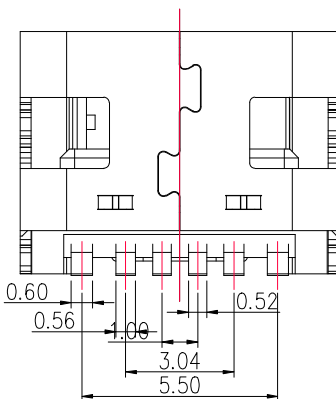
NOTE:

1. MATERIAL SPECIFICATION:
 1. HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
 2. CONTACTS: COPPER ALLOY
 3. MID PLATE: STAINLESS STEEL
 4. FRONT SHELL: STAINLESS STEEL
2. PLATING SPECIFICATION:
 - 2-1. CONTACTS: Ni 50u" MIN. UNDER PLATED OVER ALL. Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N) PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2. FRONT SHELL: SEE TABLE 1.
 - 2-3. SHIELD PLATE & EMI PLATE: CLEAR ONLY
3. MECHANICAL PERFORMANCE,
 - 3-1. INSERTION FORCE: 0.5~2.0kgf.
 - 3-2. REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3. DURABILITY: 5000 CYCLES.
4. ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 3.0A VOLTAGE RATING: 5.0V
 - 4-2. LLCR: VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX. SHIELD: 50mA/MAX. LLCR MAX. CHANGE OF ALL PINS: 10mA.
 - 4-3. INSULATION RESISTANCE: 100MΩ MIN
 - 4-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE: OPERATING TEMPERATURE: -25°C~+85°C.
6. IR REFLOW: THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



PIN ASSIGNMENTS

A5	CC1	B12	GND
A9	VBUS	B9	VBUS
A12	GND	B5	CC2
PIN	SIGNAL NAME	PIN	SIGNAL NAME



RECOMMENDED P.C.B. LAYOUT TOLERANCE UNSPECIFIED ±0.05mm

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X ±0.30 X.X ±0.20 X.XX ±0.10
 ANGLES: X ±2° X.X ±1°



东莞市汉博电子科技有限公司
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	TYPE C 6P板上四脚插板SMT L=7.4			
DWN	xiong	PART NO.	MC-312-L74	
CHKD	lee	SCALE: 1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET: 1 OF 1	REV: A4

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